

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16224	
1.3 Title of PCN	ST Shenzhen (China) additional DPS source for STM32H563x and STM32H573x listed products in WLCSP80 package	
1.4 Product Category	STM32H563x and STM32H573x in WLCSP80 package	
1.5 Issue date	2026-03-20	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Finishing (SOP 2617)	ST Shenzhen (DPS)

4. Description of change

	Old	New
4.1 Description	Current Die Processing Service sites: - ASE Kaohsiung (Taiwan) - JCAP (China)	Die Processing Service sites: - ASE Kaohsiung (Taiwan) - JCAP (China) - ST Shenzhen (China) - additional DPS site
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	- Form: Marking composition change. - Fit: No impact: - No change on WLCSP dimensions - Function: No impact	

5. Reason / motivation for change

5.1 Motivation	Additional source for DPS
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Change is visible in the marking with FT code changing from - AA :ASE Kaohsiung (Taiwan) - GN : JCAP (China) to new DPS site: - GK : ST Shenzhen Please refer to PCN 16224_Additional information.pdf document for further details.
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7. Timing / schedule

7.1 Date of qualification results	2026-09-07
7.2 Intended start of delivery	2026-09-07
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16224 MDRF-GPAM-RER2608 PCN16224 - ST Shenzhen (China) additional DPS source in WLCSP80 package - reliability plan.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-03-20
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9. Attachments (additional documentations)

16224 Public product.pdf
 16224 MDRF-GPAM-RER2608 PCN16224 - ST Shenzhen (China) additional DPS source in WLCSP80 package - reliability plan.pdf
 16224 _Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H563MIY3QTR	
	STM32H573MIY3QTR	

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